

## Patent Claims

1. Method for producing an integrated circuit (23) with a rewiring device (18, 19), having the following steps:

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provision of a carrier device (10) with predefined or subsequently patterned cutouts (11);

10 application of at least one integrated circuit (14) upside down to the carrier device (10) in such a way that the defined cutouts (11) of the carrier device (10) are located above at least one connection device (15) of the integrated circuit (14);

15 application of an insulation device (17) to that side of the carrier device (10) which is not covered by the integrated circuit (14), omitting the at least one connection device (15) in the cutout (11);

20 application of the patterned rewiring device (18, 19) to the insulation device (17);

application of a patterned solder resist device (20) to the patterned rewiring device (18, 19); and

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patterned application of solder balls (22) on sections (21) of the rewiring device (18) which are not covered by the patterned solder resist device (20).

30 2. Method according to Claim 1, characterized in that the carrier device (10) is a film in which the at least one cutout (11) is present in the form of a stamped-out hole.

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3. Method according to Claim 1 or 2, characterized

in that, before the application of the integrated circuit (14), an adhesive (12) is applied to the carrier device (10).

- 5    4.    Method according to one of the preceding claims, characterized  
in that the carrier device (10) is clamped in a clamping-in device (13) such as e.g. a frame.

- 10   5.    Method according to one of the preceding claims, characterized  
in that a multiplicity of integrated circuits (14) are applied to the carrier device (10) by means of a placement device, such as e.g. a pick-and-place tool.

- 15   6.    Method according to one of the preceding claims, characterized  
in that a protection device (16) is applied above the carrier device (10) and the at least one integrated  
20 circuit (14) applied.

7.    Method according to Claim 6, characterized  
in that the protection device (16) is applied in an  
25 injection-molding or another potting or printing process and/or is subsequently partly or completely cured.

8.    Method according to one of the preceding claims, characterized  
30 in that a polymer is applied as the insulation device (17).

9.    Method according to one of the preceding claims, characterized  
35 in that the insulation device (17) is printed on or produced in a photolithographic process.

10. Method according to one of the preceding claims,  
characterized  
in that the patterned rewiring device (18, 19) is applied  
to the insulation device (17) by means of the following  
5 steps:

application of a carrier metallization to the insulation  
device (17);

10 application and patterning of a mask on the carrier  
metallization;

application of a conductor track metallization in regions  
of the carrier metallization which are not covered by the  
15 patterned mask;

removal of the mask; and

patterning of the carrier metallization in accordance  
20 with the conductor track metallization structure.

11. Method according to Claim 10,  
characterized

in that the carrier metallization is sputtered on and/or  
25 the mask is patterned photolithographically and/or the  
conductor track metallization (18) is electrochemically  
plated and/or the carrier metallization is patterned in  
an etching step.

30 12. Method according to one of the preceding claims,  
characterized  
in that the solder resist device (20) has a polymer.

13. Method according to one of the preceding claims,  
35 characterized  
in that the solder resist device (20) is printed on.

14. Method according to one of the preceding claims,  
characterized

in that the solder balls (22) are applied in patterned  
fashion in a printing process and are subsequently  
5 reliefs, preferably in a reflow furnace.

15. Method according to one of the preceding claims,  
characterized

in that a multiplicity of integrated circuits (14) on a  
10 carrier device (10), after the application of the solder  
balls (22), are separated into individual integrated  
circuits (23) or groups of integrated circuits (23).

16. Method according to Claim 15,

15 characterized

in that a multiplicity of integrated circuits (14, 23)  
with rewiring devices (18, 19) on the carrier device (10)  
undergo a functional test prior to the separation.

20 17. Method according to one of the preceding claims,  
characterized

in that the patterned rewiring device (18, 19) is  
patterned in such a way that it extends laterally beyond  
the integrated circuit (14).

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18. Method according to one of the preceding claims,  
characterized

in that multichip modules are formed, which preferably  
have different individual ICs.

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19. Integrated circuit (23) with a rewiring device (18,  
19), having:

a carrier device (10) with predefined or subsequently  
35 patterned cutouts (11);

at least one integrated circuit (14) upside down on the carrier device (10) in such a way that the defined cutouts (11) of the carrier device (10) are located above at least one connection device (15) of the  
5 integrated circuit (14);

an insulation device (17) on that side of the carrier device (10) which is not covered by the integrated circuit (14), omitting the at least one connection device  
10 (15) in the cutout (11);

the patterned rewiring device (18, 19) on the insulation device (17);

15 a patterned solder resist device (20) on the patterned rewiring device (18, 19); and

solder balls (22) on sections (21) on the rewiring device (18) which are not covered by the patterned solder resist  
20 device (20).